UTC UNISONIC TECHNOLOGIES CO., LTD

MJE13003-P

NPN SILICON TRANSISTOR

NPN SILICON POWER TRANSISTOR

DESCRIPTION

These devices are designed for high-voltage and high-speed power switching inductive circuits where fall time is critical. They are particularly suited for 115 and 220V applications in switch mode.

FEATURES

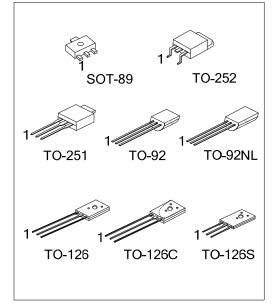
* Reverse biased SOA with inductive load @ Tc=100°C

- * Inductive switching matrix 0.5 ~ 1.5 Amp, 25 and 100°C
- Typical tc = 290ns @ 1A, 100°C.
- * 700V blocking capability

APPLICATIONS

- * Switching regulator's, inverters
- * Motor controls
- * Solenoid/relay drivers
- * Deflection circuits

ORDERING INFORMATION

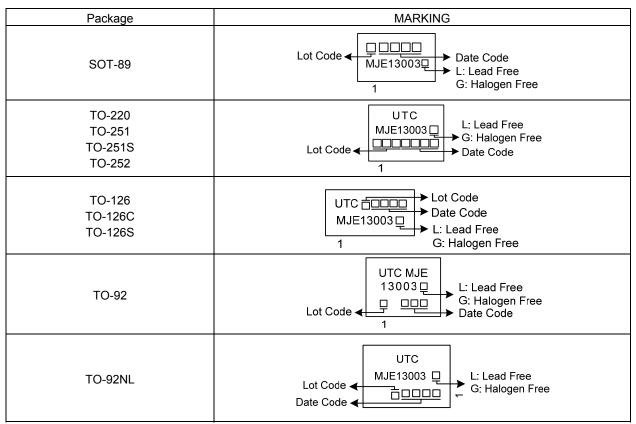


Ordering Number		Package	Pin Assignment			Dooking
Lead Free	Halogen-Free Package		1	2	3	Packing
MJE13003L-P-x-AB3-R	MJE13003G-P-x-AB3-R	SOT-89	В	С	Е	Tape Reel
MJE13003L-P-x-T60-K	MJE13003G-P-x-T60-K	TO-126	В	С	Е	Bulk
MJE13003L-P-x-T6C-A-K	MJE13003G-P-x-T6C-A-K	TO-126C	Е	С	В	Bulk
MJE13003L-P-x-T6C-F-K	MJE13003G-P-x-T6C-F-K	TO-126C	В	С	Е	Bulk
MJE13003L-P-x-T6S-K	MJE13003G-P-x-T6S-K	TO-126S	В	С	Е	Bulk
MJE13003L-P-x-T92-B	MJE13003G-P-x-T92-B	TO-92	Е	С	В	Tape Box
MJE13003L-P-x-T92-K	MJE13003G-P-x-T92-K	TO-92	Е	С	В	Bulk
MJE13003L-P-x-T92-R	MJE13003G-P-x-T92-R	TO-92	Е	С	В	Tape Reel
MJE13003L-P-x-T9N -B	MJE13003G-P-x-T9N-B	TO-92NL	Е	С	В	Tape Box
MJE13003L-P-x-T9N -K	MJE13003G-P-x-T9N-K	TO-92NL	Е	С	В	Bulk
MJE13003L-P-x-T9N -R	MJE13003G-P-x-T9N-R	TO-92NL	Е	С	В	Tape Reel
MJE13003L-P-x-TM3-T	MJE13003G-P-x-TM3-T	TO-251	В	С	Е	Tube
MJE13003L-P-x-TN3-R	MJE13003G-P-x-TN3-R	TO-252	В	С	Е	Tape Reel
Note: Pin assignment: B: Base	C: Collector E: Emitter					

MJE13003G-P-x-T6C-A-K (1)Packing Type (2)Pin Assignment (3)Package Type (4)Rank (5)Green Package	(1) R: Tape Reel, K: Bulk, B: Tape Box, T: Tube (2) refer to Pin Assignment (for TO-126C) (3) T60: TO-126, T6C:TO-126C, T6S: TO-126S T92: TO-92, T9N: TO-92NL, TM3: TO-251, TN3: TO-252 (4) x: refer to Classification of h_{FE1} (5) G: Halogen Free and Lead Free, L: Lead Free
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NPN SILICON TRANSISTOR

MARKING





■ ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	RATINGS	UNIT		
Collector-Emitter Voltage		V _{CEO(SUS)}	400	V		
Collector-Emitter Voltage (V _{BE} =0)		V _{CES}	700	V		
Collector-Base Voltage			V _{CBO}	700	V	
Emitter Base Voltage			V _{EBO}	9	V	
Collector Current Continuous Peak (1)		Continuous	Ι _C	1.5	— A	
		Peak (1)	I _{CM}	3		
Base Current		Continuous	IB	0.75	— A	
Dase Current		Peak (1)	I _{BM}	1.5	A	
		Continuous	Ι _Ε	2.25	— A	
Emitter Current	-	Peak (1)	I _{EM}	4.5	A	
	T _A =25°C TO-126S TO-92/TO-92NL TO-251/TO-252	SOT-89		0.5	W	
		TO-126/TO-126C		1.4	W	
		TO-126S		1.4	vv	
		TO-92/TO-92NL		1.1	W	
Total Dowor Dissinction		TO-251/TO-252	P _D —	1.56	W	
Total Power Dissipation	T _C =25°C	SOT-89	FD	1.64	W	
		TO-126/TO-126C		20	W	
		TO-126S		20	vv	
		TO-92/TO-92NL		1.5	W	
		TO-251/TO-252		25	W	
Junction Temperature		TJ	+150	°C		
Storage Temperature			T _{STG}	-55 ~ +150	°C	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.



NPN SILICON TRANSISTOR

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS (Note)								
Collector-Emitter Sustaining Voltage		V _{CEO(SUS)}	I _C =10 mA , I _B =0	400			V	
Collector Cutoff Current	T _C =25°C		V _{CEO} =Rated Value,			1		
	T _C =100°C	I _{CEO}	V _{BE(OFF)} =1.5 V			5	mA	
Emitter Cutoff Current	· -	I _{EBO}	V _{EB} =9 V, I _C =0			1	mA	
SECOND BREAKDOWN								
Second Breakdown Collector Curren	t with bass	ls/b	See Fig.5					
forward biased								
Clamped Inductive SOA with base re	everse biased	RB _{SOA}	See Fig.6		.6			
ON CHARACTERISTICS (Note)		1.		1		i		
DC Current Gain		h _{FE1}	I _C =0.4A, V _{CE} =5V	14		32	-	
		h _{FE2}	I _C =1A, V _{CE} =5V	5		30		
			I _C =0.5A, I _B =0.1A			0.5		
Collector-Emitter Saturation Voltage		V _{CE(SAT)}	I _C =1A, I _B =0.25A			1	v	
		VCE(SAT)	I _C =1.2A, I _B =0.4A			3		
			I _C =1A, I _B =0.25A, T _C =100°C			1		
			I _C =0.5A, I _B =0.1A			1		
Base-Emitter Saturation Voltage		$V_{\text{BE(SAT)}}$	I _C =1A, I _B =0.25A			1.2	V	
			I _C =1A, I _B =0.25A, T _C =100°C			1.1]	
DYNAMIC CHARACTERISTICS								
Current-Gain-Bandwidth Product		f⊤	I _C =100mA, V _{CE} =10V, f=1MHz	4	10		MHz	
Output Capacitance		C _{OB}	V _{CB} =10V, I _E =0, f=0.1MHz		21		рF	
SWITCHING CHARACTERISTICS								
Resistive Load (Table 1)								
Delay Time		t _D			0.05	0.1	μs	
Rise Time Storage Time Fall Time		t _R	V _{CC} =125V, I _C =1A, I _{B1} =I _{B2} =0.2A,		0.5	1	μs	
		ts	t _P =25µs, Duty Cycle≤1%		2	4	μs	
		t _F			0.4	0.7	μs	
Inductive Load, Clamped (Table 1)					_	_		
Storage Time		t _{stg}			1.7	4	μs	
Crossover Time		t _c	I_{C} =1A, Vclamp=300V, I_{B1} =0.2A,		0.29	0.75	μs	
Fall Time		t _F	V _{BE(OFF)} =5Vdc, T _C =100°C		0.15		μs	
Nate: Dulas Test (DM-2000s, Duty)	a iaa/	•	•			-	· · · · · ·	

■ ELECTRICAL CHARACTERISTICS (T_c=25°C, unless otherwise specified.)

Note: Pulse Test : PW=300µs, Duty Cycle≤2%

■ CLASSIFICATION OF h_{FE1}

RANK	А	В	С
RANGE	14 ~ 22	21 ~ 27	26 ~ 32



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APPLICATION INFORMATION

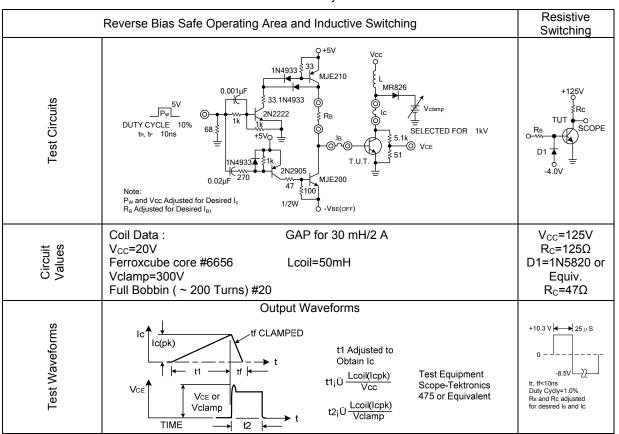


Table 1.Test Conditions for Dynamic Performance

Table 2. Typical Inductive Switching Performance

Ic	Tc	t _{sv}	t _{RV}	t _{Fl}	t _{τι}	tc
(A)	(°C)	(μs)	(μs)	(μs)	(μs)	(μs)
0.5	25	1.3	0.23	0.30	0.35	0.30
	100	1.6	0.26	0.30	0.40	0.36
1	25	1.5	0.10	0.14	0.05	0.16
	100	1.7	0.13	0.26	0.06	0.29
1.5	25	1.8	0.07	0.10	0.05	0.16
	100	3	0.08	0.22	0.08	0.28

Note: All Data Recorded in the Inductive Switching Circuit in Table 1

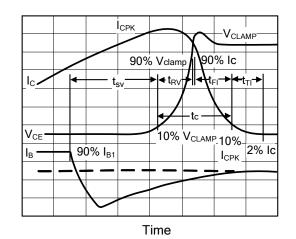


Fig.1 Inductive Switching Measurements



SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads, which are common to switch mode power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

 t_{SV} = Voltage Storage Time, 90% I_{B1} to 10% Vclamp

 t_{RV} = Voltage Rise Time, 10 ~ 90% Vclamp

 $t_{\text{FI}}\text{=}$ Current Fall Time, 90 ~ 10% I_{C}

 t_{TI} = Current Tail, 10 ~ 2% I_C

 t_{C} = Crossover Time, 10% Vclamp to 10% I_{C}

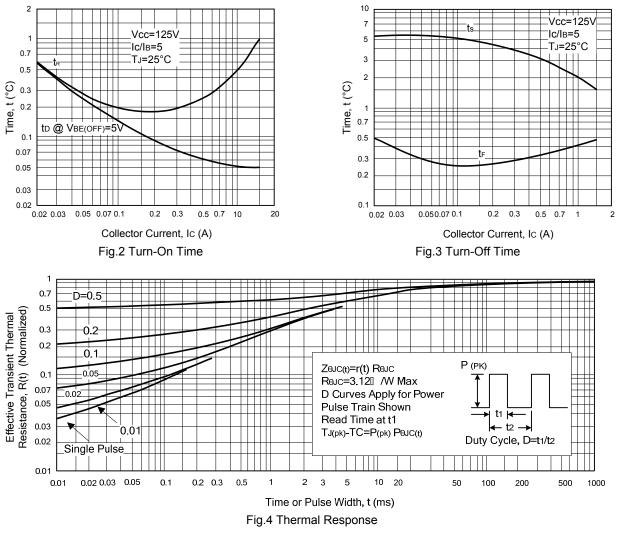
For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation:

 P_{SWT} = 1/2 $V_{CC}I_C$ (t_c) f

In general, $t_{RV} + t_{FI} \approx t_C$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this transistor are the inductive switching speeds (t_c and t_{sv}) which are guaranteed at 100°C.

RESISTIVE SWITCHING PERFORMANCE





SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_{C}-V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

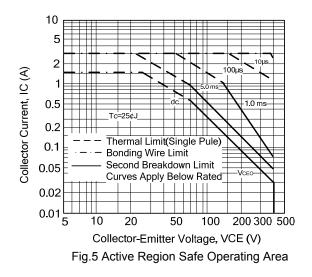
The data of Fig.5 is based on $T_C = 25^{\circ}C$; $T_{J(PK)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25^{\circ}C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Fig.5.

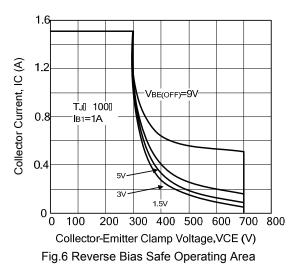
 $T_{J(PK)}$ may be calculated from the data in Fig.4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as RB_{SOA} (Reverse Bias Safe Operating Area) and represents the voltage-current conditions during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Fig.6 gives RB_{SOA} characteristics.

The Safe Operating Area of Fig.5 and 6 are specified ratings (for these devices under the test conditions shown.)

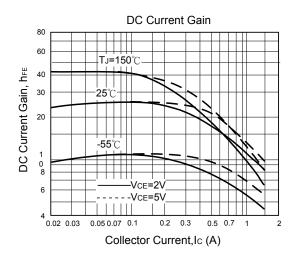


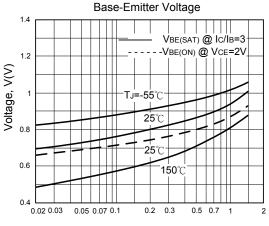


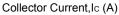


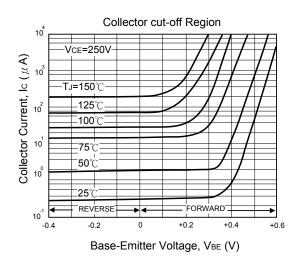
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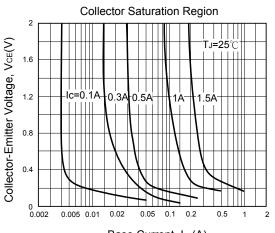
TYPICAL CHARACTERISTICS



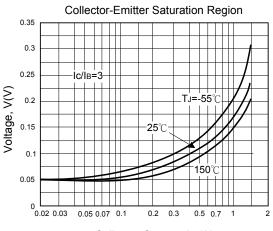




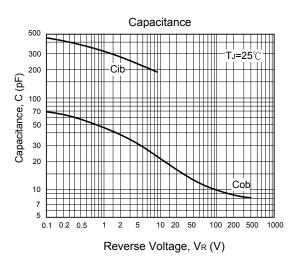




Base Current, IB (A)



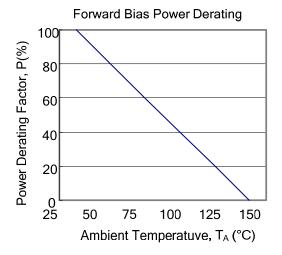






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TYPICAL CHARACTERISTICS(Cont.)



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